Launched

2

4

2.3 GHz

35 W

16 GB

21.3 GB/s

650 MHz

1.15 GHz

Yes

Yes

No

2

2.0

16

1

32 nm

No

No

Q

Q

Q

Q No

Yes

Q No

PPGA988

See MDDS

1x16, 2x8, 1x8 2x4

85C (PGA); 100C (BGA)

37.5mm x 37.5mm (rPGA988B);

31mm x 24mm (BGA1023)

2

Q No

Q

Q

DDR3 1066/1333

Intel® HD Graphics 3000

eDP/DP/HDMI/SDVO/CRT

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916669; PCN | MDDS

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Intel® Core™ i3-2350M Processor

(3M Cache, 2.30 GHz)

Specifications Specifications | Essentials Essentials Performance Status Memory Specifications Launch Date Graphics Specifications **Expansion Options** Package Specifications Advanced Technologies DMI Intel® Data Protection Technology

Intel® Platform

Protection Technology

Compatible Products

Ordering / sSpecs /

Product Images

Steppings

Q4'11 Processor Number i3-2350M Intel® Smart Cache 3 МВ 5 GT/s 64-bit Instruction Set AVX. Instruction Set Extensions Q No Embedded Options Available

Lithography 32 nm Recommended Customer Price TRAY: \$225.00 Datasheet Link

 Performance # of Cores

of Threads Processor Base Frequency TDP Memory Specifications

Max Memory Size (dependent on memory type) Memory Types Max # of Memory Channels Max Memory Bandwidth

 Graphics Specifications Processor Graphics # Graphics Base Frequency Graphics Max Dynamic Frequency

Graphics Output

ECC Memory Supported *

Intel® Quick Sync Video Intel® InTru™ 3D Technology Intel® Insider™ Intel® Wireless Display Intel® Flexible Display Interface (Intel® FDI)

Intel® Clear Video HD Technology Macrovision* License Required # of Displays Supported * Expansion Options

PCI Express Configurations * Max # of PCI Express Lanes Package Specifications

Max CPU Configuration TJUNCTION Package Size Graphics and IMC Lithography Sockets Supported

Low Halogen Options Available

Intel® Virtualization Technology for Directed I/O

PCI Express Revision

 Advanced Technologies Intel® Turbo Boost Technology # Intel® vPro Technology # Intel® Hyper-Threading Technology * Intel® Virtualization Technology (VT-x) *

(VT-d) #

Intel® VT-x with Extended Page Tables (EPT) * Intel® 64 * Intel® My WiFi Technology 4G WiMAX Wireless Technology Idle States

Enhanced Intel SpeedStep® Technology Intel® Demand Based Switching Thermal Monitoring Technologies Intel® Fast Memory Access

Intel® Flex Memory Access Intel® Identity Protection Technology # Intel® Data Protection Technology AES New Instructions

Intel® Platform Protection Technology

compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

Trusted Execution Technology *

Execute Disable Bit * Anti-Theft Technology

Q No

Q No

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Refer to Datasheet for formal definitions of product properties and features. "Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

classification of any item at the time of export.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update. ‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard,

processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration. 'Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum,

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Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content /www/us/en/processors/processor-numbers.html for details.

For benchmarking data see http://www.intel.com/performance.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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